Polishing slurry for the chemical-mechanical polishing of silica films

Abstract

A polishing slurry for chemical-mechanical polishing, containing 5 to 50% by weight of a colloidal silica abrasive, and 0.1 to 10% by weight of a quaternary ammonium salt which is represented by the formula $R_4N^+X^-$, where R may be identical or different and is selected from the group consisting of alkyl, alkenyl, alkylaryl, arylalkyl and an ester group, and X is hydroxyl or halogen, is distinguished by a high polishing rate.